L Number	Hits	Search Text	DB	Time stamp
- Namber	22		USPAT;	2004/09/19 12:11
1			US-PGPUB;	, ,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	53	((immobile) same (chelat\$4))	USPAT;	2004/09/19 12:16
			US-PGPUB; EPO; JPO;	·
			DERWENT;	
			IBM TDB	
_	31	(((immobile) same (chelat\$4))) not	USPAT;	2004/09/19 12:19
		(((immobile) with (chelat\$4)))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		///www.hila.v. and /ah-lah04v.v	IBM_TDB	0004/00/10 10 00
_	911	((immobile) and (chelat\$4))	USPĀT; US-PGPUB;	2004/09/19 13:32
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	(((immobile) and (chelat\$4))) and	USPĀT;	2004/09/19 12:18
		((immobile adj particle\$1) and (chelat\$4))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1.00	////	IBM_TDB	0004/00/10 10 10
-	193	(((immobile) and (chelat\$4))) and ((immobile) and (chelating adj agent))	USPAT; US-PGPUB;	2004/09/19 12:18
1		((Immobile) and (Chefating adjagent))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	172	((((immobile) and (chelat\$4))) and	USPAT;	2004/09/19 12:30
		((immobile) and (chelating adj agent)))	US-PGPUB;	
		not ((((immobile) same (chelat\$4))) or	EPO; JPO;	
		(((immobile) with (chelat\$4))))	DERWENT;	
1_	686	(((immobile) and (chelat\$4))) not	IBM_TDB USPAT;	2004/09/19 12:47
_	000	(((((immobile) and (chelat\$4))) and	US-PGPUB;	2004/09/19 12:4/
		((immobile) and (chelating adj agent))) or	EPO; JPO;	
		(((immobile) same (chelat\$4))) or	DERWENT;	
		(((immobile) with (chelat\$4))))	IBM_TDB	
-	45085	ibm.as.	USPAT;	2004/09/19 12:48
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	265	international-business-machines.as.	USPAT;	2004/09/19 15:29
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	4001.		IBM_TDB	0004/00/10 10 1
-	48814	1	USPĀT;	2004/09/19 12:51
		machines.as.	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	93874	ibm.as. or	USPAT;	2004/09/19 12:51
		international-business-machines.as. or	US-PGPUB;	
		(international adj business adj	EPO; JPO;	
		machines.as.)	DERWENT;	
	80	/ibm as or	IBM_TDB	2004/00/10 14-50
-	80	(ibm.as. or international-business-machines.as. or	USPAT; US-PGPUB;	2004/09/19 14:59
		(international adj business adj	EPO; JPO;	
		machines.as.)) and immobile	DERWENT;	
			IBM TDB	
-	171	(ibm.as. or	USPAT;	2004/09/19 13:32
		international-business-machines.as. or	US-PGPUB;	
		(international adj business adj	EPO; JPO;	[
		machines.as.)) and chelat\$4	DERWENT;	~
	L	l	IBM TDB	L

-	4	((ibm.as. or	USPAT;	2004/09/19 12:52
		international-business-machines.as. or	US-PGPUB;	
		(international adj business adj	EPO; JPO;	
		machines.as.)) and immobile) and ((ibm.as. or international-business-machines.as. or	DERWENT;	
		(international adj business adj	IBM_TDB	
		machines.as.)) and chelat\$4)		
! _	171		USPAT;	2004/09/19 13:12
	1/1	international-business-machines.as. or	US-PGPUB;	2004/03/13 13:12
		(international adj business adj	EPO; JPO;	
		machines.as.)) and chelat\$4) not	DERWENT;	
	1	((((174/260) or (174/256) or (174/52.2) or	IBM TDB	
		(264/272.11) or (438/126) or (438/127) or	_	
		(257/778) or (257/779) or (257/772) or		
		(257/789) or (257/780) or (257/787) or		
		(257/788) or (257/795) or		
		(257/632)).CCLS.) and ((immobile) and		
	10605	(chelat\$4)))	IICDAM.	2004/00/10 17:20
-	18685	immobile	USPAT;	2004/09/19 17:29
			US-PGPUB; EPO; JPO;	
			DERWENT;	
	İ		IBM TDB	
-	104966	chelat\$4	USPAT;	2004/09/19 13:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1906629	(USPAT;	2004/09/19 13:37
		adj circuit) or (semiconductor adj device)	US-PGPUB;	
		or (electronic adj component) or	EPO; JPO;	
		(electroinc adj device) or (printed adj	DERWENT;	
		circuit) or (printed adj wiring) or (circuit adj board)	IBM_TDB	
F _	105		USPAT;	2004/09/19 13:48
	103	(wafer) or (ic) or (integrated adj	US-PGPUB;	2004/09/19 13.48
		circuit) or (semiconductor adj device) or	EPO; JPO;	
		(electronic adj component) or (electroinc	DERWENT;	
		adj device) or (printed adj circuit) or	IBM TDB	
		(printed adj wiring) or (circuit adj	_	
		board))		
-	1401		USPAT	2004/09/19 14:04
		<pre>(integrated adj circuit) or (semiconductor adj device) or (electronic adj component)</pre>		
		or (electroinc adj device) or (printed adj		
		circuit) or (printed adj wiring) or		
1		(circuit adj board))		
-	6300		USPAT	2004/09/27 11:59
		(integrated adj circuit) or (semiconductor		
		adj device) or (electronic adj component)		
1		or (electroinc adj device) or (printed adj		
		circuit) or (printed adj wiring) or		
l _	53	(circuit adj board))	IIODAM .	2004/00/10 14:15
l ⁻	33	(immobile and ((chip) or (wafer) or (ic) or (integrated adj circuit) or	USPAT	2004/09/19 14:16
		(semiconductor adj device) or (electronic		
		adj component) or (electroinc adj device)		
		or (printed adj circuit) or (printed adj		
		wiring) or (circuit adj board))) and		
		(chelat\$4 and ((chip) or (wafer) or (ic)		
1		or (integrated adj circuit) or		
		(semiconductor adj device) or (electronic		
		adj component) or (electroinc adj device)		
		or (printed adj circuit) or (printed adj		
<u>_</u>	1137	wiring) or (circuit adj board))) chelat\$4 and (174/\$.ccls. or 29/\$.ccls. or	USPAT	2004/09/19 14:49
	113/	257/\$.ccls. or 361/\$.ccls.)	OSERI	2004/03/13 14.43
_	2		USPAT	2004/09/19 14:58
	_	or 257/\$.ccls. or 361/\$.ccls.)) and		
		immobile		

_	14	(composition) with (immobile) with (chelat\$ or complex\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/19 17:44
-	747	or (integrated adj circuit) or (semiconductor adj device) or (electronic	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/19 15:31
		adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)	DERWENT; IBM_TDB	
-	74	((chelat\$4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electronic adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)) and (high adj molecular adj weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 16:04
-	28	immobile adj particle\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 17:29
-	42	<pre>(composition) same (immobile) same (chelat\$ or complex\$4)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 17:45
-	28	<pre>((composition) same (immobile) same (chelat\$ or complex\$4)) not ((composition) with (immobile) with (chelat\$ or complex\$4))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 17:48
-	26564	chelating adj agent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 10:48
-	11884	<pre>(chelating adj agent) or (immobile adj particle\$1)</pre>	USPAT	2004/09/24 10:51
-	0	(chelating adj agent) and (immobile adj particle\$1)	USPAT	2004/09/24 10:51
-	28	immobile adj particle\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 15:23
_	746	(composition) with (metal adj ion\$1) with (chelat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 17:37
_	2	(composition) with (metal adj ion\$1) with (chelat\$4) with (Immobile adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 17:39
-	3	(composition) with (metal adj ion\$1) with (chelat\$4) with (Immobile)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 17:44
- -	0 1	("4and(chelat\$1)and(particle\$1)").PN. (("4707453").PN.) and (chelat\$1) and	USPAT USPAT	2004/09/24 17:46 2004/09/24 17:50
_	62	<pre>(particle\$1) ((composition) with (metal adj ion\$1) with (chelat\$4)) and (package)</pre>	USPAT	2004/09/24 17:51

_	1	((("4707453").PN.) and (chelat\$1) and	USPAT	2004/09/24 18:04
	,	(particle\$1)) and (package)	HCDam	2004/00/24 10:05
-	$\frac{1}{3}$	(particle\$1 adj chelat\$4) and package (particle\$1 adj chelat\$4) and package	USPAT USPAT	2004/09/24 18:05 2004/09/24 18:17
1	5	(particle\$1 adj chelat\$4) and package	USPAT;	2004/09/24 18:17
		(partitioner adj enclatiff and package	US-PGPUB	2004/03/24 10:07
_	6	(particle\$1 adj chelat\$4) and package	USPAT;	2004/09/24 18:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	0	(("6711423").PN.) and (particle\$1 adj	USPAT	2004/09/24 18:17
	0	chelat\$4) (("6711423").PN.) and (immobile)	HODAM	2004/00/24 10:17
<u>-</u>	1	(("6711423").PN.) and (chelat\$4)	USPAT USPAT	2004/09/24 18:17 2004/09/24 18:20
_	4540	(chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/24 16:20
		or ethylenediamine or oxylate)	US-PGPUB	2001,03,20 10112
-	587	((chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/25 16:46
		or ethylenediamine or oxylate)) and	US-PGPUB	
		(electronic adj device or integrated adj		
		circuit or package or printed adj circuit		
		adj board or printed adj wiring adj board or semiconductor adj device or		
		or semiconductor adj device or semiconductor adj package)		
_	156	((chelat\$4) with (epta or ethylenediamine	USPAT:	2004/09/25 16:46
		or ethylenediamine or oxylate)) and	US-PGPUB	
		(immobile)		
-	10	(((chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/25 16:54
		or ethylenediamine or oxylate)) and	US-PGPUB	
		(electronic adj device or integrated adj		
		circuit or package or printed adj circuit adj board or printed adj wiring adj board		
		or semiconductor adj device or		
		semiconductor adj package)) and		
		(((chelat\$4) with (epta or ethylenediamine		
		or ethylenediamine or oxylate)) and		
		(immobile))		
-	945	((chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/25 16:55
		or ethylenediamine or oxylate)) and (high adj molecular adj weight)	US-PGPUB	
_	106	(((chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/26 13:16
	100	or ethylenediamine or oxylate)) and	US-PGPUB	2004/05/20 15:10
		(electronic adj device or integrated adj		
		circuit or package or printed adj circuit		
		adj board or printed adj wiring adj board		
		or semiconductor adj device or		
		<pre>semiconductor adj package)) and (((chelat\$4) with (epta or ethylenediamine</pre>		
		or ethylenediamine or oxylate)) and (high		
		adj molecular adj weight))		
-	1239	kline.in.	USPAT	2004/09/25 17:30
-	24	kline.in. and (chelat\$4)	USPAT	2004/09/25 17:48
-	136	(integrated adj circuit) with (scratch)	USPAT;	2004/09/25 18:38
_	286	(integrated add girguit) with (sometable)	US-PGPUB	2004/00/25 10:20
-	286	(integrated adj circuit) with (scratch\$4)	USPAT; US-PGPUB	2004/09/25 18:38
_	136	((integrated adj circuit) with (scratch))	USPAT;	2004/09/25 18:39
	155	and ((integrated adj circuit) with	US-PGPUB	2001, 05, 25 10.59
		(scratch\$4))		
-	286	((integrated adj circuit) with (scratch))	USPAT;	2004/09/25 18:39
		or ((integrated adj circuit) with	US-PGPUB	
		(scratch\$4))		0004/00/05 10 15
ļ ⁻	10	(((integrated adj circuit) with (scratch))	USPAT;	2004/09/25 18:40
		<pre>or ((integrated adj circuit) with (scratch\$4))) and chelat\$4</pre>	US-PGPUB	
_	o	("(wateradjpollutionadjmonitoring)with(cheld	e fissepath) PN	2004/09/27 11:55
-	1	(water adj pollution adj monitoring) with	USPAT	2004/09/27 11:56
	_	(chelat\$4)		
-	1119	(analy\$6) with (chelat\$4)	USPAT	2004/09/27 11:57
-	614	((analy\$6) with (chelat\$4)) and (metal adj	USPAT	2004/09/27 11:57
		ion\$4)		

-	624		USPAT	2004/09/27 11:58
		adj ion\$4)		
-	327	' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT	2004/09/27 11:59
		adj ion\$4)) and (chelating adj agent)		
-	46	1111 2111 1	USPAT	2004/09/27 12:22
		adj ion\$4)) and (chelating adj agent)) and		
	İ	((chip) or (wafer) or (ic) or (integrated		
		adj circuit) or (semiconductor adj device)		
		or (electronic adj component) or		
İ		(electroinc adj device) or (printed adj		
		circuit) or (printed adj wiring) or		
		(circuit adj board))		
-	428	604/\$.ccls. and (chelat\$4)	USPAT	2004/09/27 13:38
i -	9	(604/\$.ccls. and (chelat\$4)) and	USPAT	2004/09/27 13:44
		(integrated adj circuit or semiconductor		
		adj chip or integrated adj circuit)		
-	448	427/\$.ccls. and (chelating adj agent)	USPAT	2004/09/27 14:03
-	2838	427/\$.ccls. and (integrated adj circuit)	USPAT	2004/09/27 14:04
j -	7174	427/\$.ccls. and (chip or wafer)	USPAT	2004/09/27 14:04
-	43	(427/\$.ccls. and (chelating adj agent))	USPAT	2004/09/27 14:57
		and (427/\$.ccls. and (chip or wafer))		
-	407	(((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:42
		(encapsul\$6)		
-	297	((((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:22
		(encapsul\$6)) and package		
-	109	(((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:42
		(underfill)		
-	43	(((((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:56
		(encapsul\$6)) and package) and		
		((((174/260) or (361/760)).CCLS.) and		
	l	(underfill))		